



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	11/25/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MGDP*XLAA51D	A	Z7GA	11/25/2014
Amount	UoM	Unit type	ST ECOPACK Grade	
5.259	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	2X2X0.50	8	flat	
Comment	Package: UDFN/COL 2X2X0.5 6L PITCH 0.65; MD valid for STTS751-1DP3F			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MGDP*XLAA51D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.402	mg	Supplier	Silicon Die	Si	7440-21-3		0.402	mg	1000000	76440
Leadframe	Copper & its alloys	1.282	mg	Supplier	Alloy	Cu	7440-50-8		1.255	mg	978939	238639
						Ni	7440-02-0		0.016	mg	12480	3042
						Zn	7440-66-6		0.003	mg	2340	570
						Cr	7440-47-3		0.003	mg	2340	570
						Sn	7440-31-5		0.003	mg	2340	570
						Au	7440-57-5		0.001	mg	780	190
						Pd	7440-05-3		0.001	mg	780	190
Die Attach	Other Organic Materials	0.115	mg	supplier	Glue	Aluminum oxide	1344-28-1		0.04	mg	347826	7606
						Diethylene glycol monoethyl ether acetate	112-15-2		0.035	mg	304348	6655
						Epoxy resin	Proprietary		0.034	mg	295652	6465
						Amine	Proprietary		0.006	mg	52174	1141
Bonding wire	Other inorganic materials	0.04	mg	supplier	Bonding wire	Gold	7440-57-5		0.04	mg	199005	7606
Encapsulation	Other Organic Materials	3.42	mg	supplier	Molding compound	Silica fused	60676-86-0		3.095	mg	949678	588515
Encapsulation						Epoxy resin	Proprietary		0.161	mg	800995	30614
Encapsulation						Phenol resin	Proprietary		0.161	mg	49402	30614
Encapsulation						Carbon black	1333-86-4		0.003	mg	921	570